

Title (en)  
PROCESS FOR MANUFACTURING A COMPONENT, ASSEMBLY, AND METHOD FOR ELECTRICALLY CONTACTING THE PRINTED CIRCUIT BOARD OF THE COMPONENT OR OF THE ASSEMBLY

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINES BAUTEILS, BAUGRUPPE UND VERFAHREN ZUR ELEKTRISCHEN KONTAKTIERUNG DER LEITERPLATTE DES BAUTEILS ODER DER BAUGRUPPE

Title (fr)  
PROCÉDÉ DE FABRICATION D'UNE PIÈCE

Publication  
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Application  
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Abstract (en)  
[origin: WO2021234146A2] The invention relates to a method for producing a component (1) which comprises a printed circuit board (2) and a plurality of electrical components (3) arranged thereon. According to the invention, the electrical components (3) are pre-fixed on the printed circuit board made of plastic by means of a fixing adhesive (9) and are subsequently fully cast with a UV adhesive (8).

IPC 8 full level  
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See references of WO 2021234146A2

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